



SBR02U100LP

0.2A SBR[®]

Surface Mount Super Barrier Rectifier

Features

- Ultra Low Forward Voltage Drop
- Superior Reverse Avalanche Capability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: DFN1006-2
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Dot
- Terminals: Finish - NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.001 grams

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_{RM}		
RMS Reverse Voltage	$V_{R(RMS)}$	70	V
Average Rectified Output Current (See Figure 1)	I_O	250	mA
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	5	A
Maximum Thermal Resistance			
Thermal Resistance, Junction to Ambient (Note 2) $T_A = 25^\circ\text{C}$	$R_{\theta JA}$	270	$^\circ\text{C/W}$
Thermal Resistance, Junction to Ambient (Note 3) $T_A = 25^\circ\text{C}$	$R_{\theta JA}$	235	
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

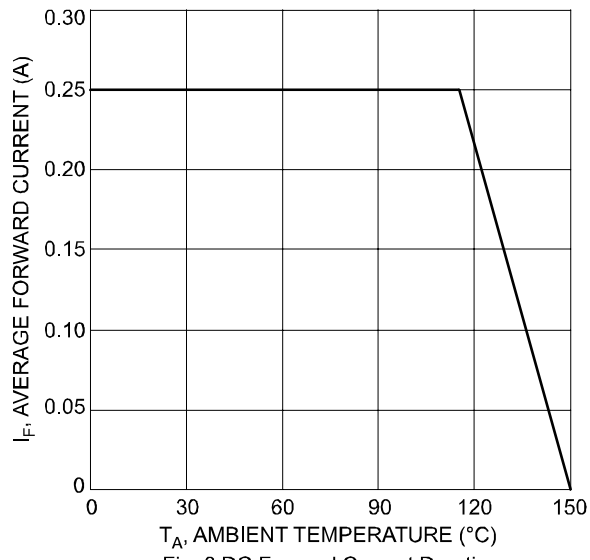
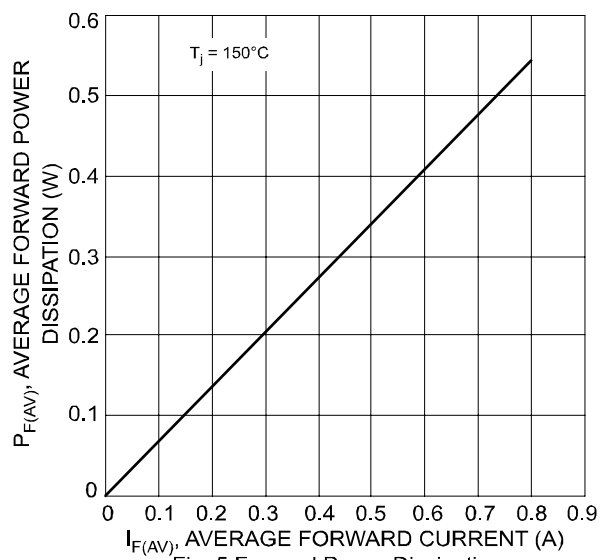
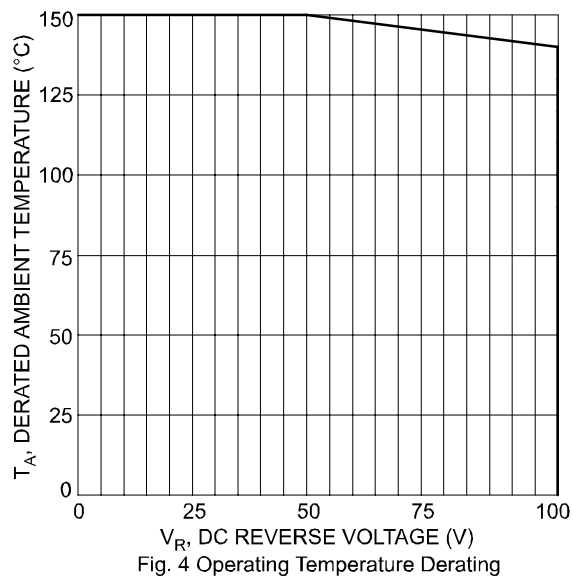
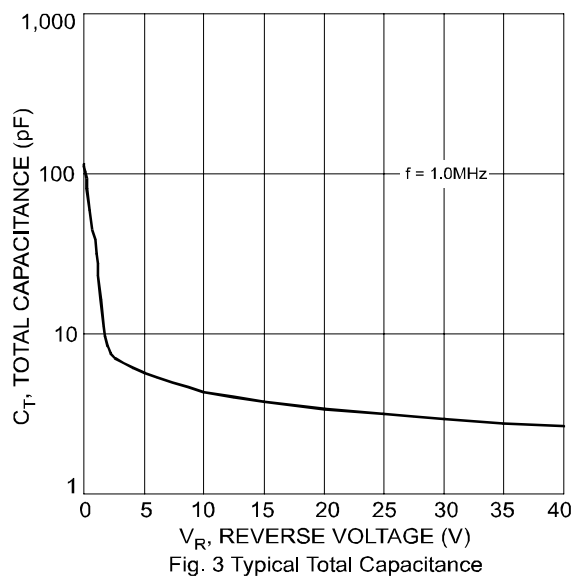
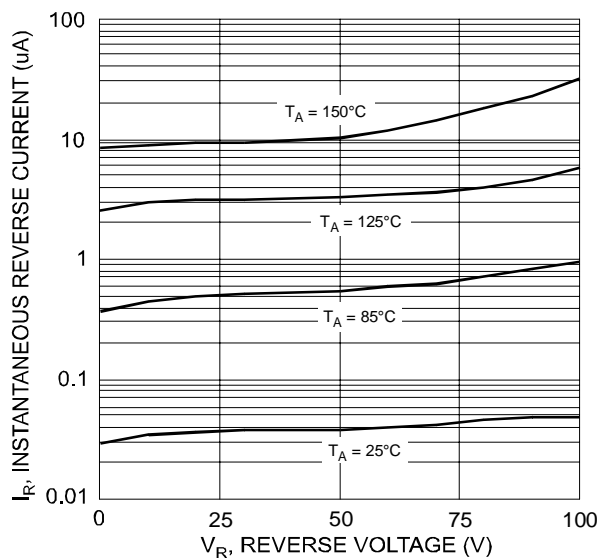
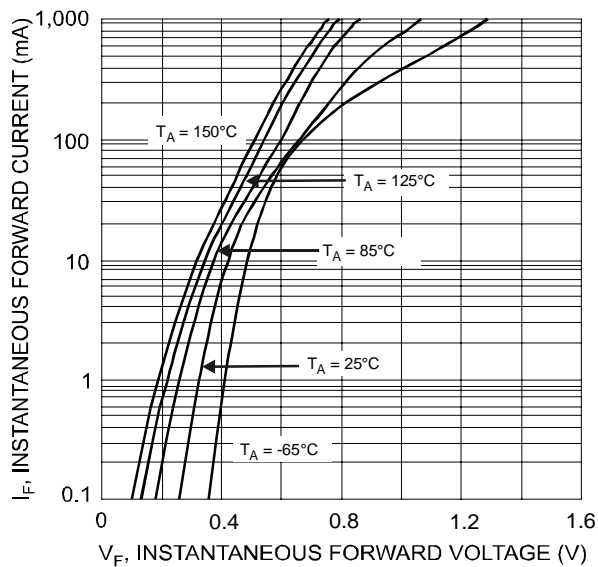
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	$V_{(BR)R}$	100	-	-	V	$I_R = 1\text{mA}$
Forward Voltage Drop	V_F	-	0.67 0.76 0.60	0.72 0.80 0.65	V	$I_F = 100\text{mA}, T_j = 25^\circ\text{C}$ $I_F = 200\text{mA}, T_j = 25^\circ\text{C}$ $I_F = 200\text{mA}, T_j = 125^\circ\text{C}$
Leakage Current (Note 4)	I_R	-	0.04 6	1.0 50	μA	$V_R = 75\text{V}, T_j = 25^\circ\text{C}$ $V_R = 75\text{V}, T_j = 85^\circ\text{C}$

- Notes:
1. RoHS revision 13.2.2003. High temperature solder exemption applied, see *EU Directive Annex Note 7*.
 2. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>
 3. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>
 4. Short duration pulse test used to minimize self-heating effect.





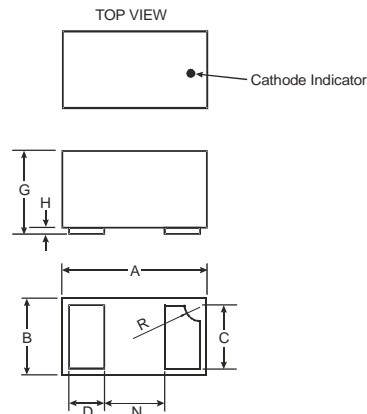
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Package Outline Drawing



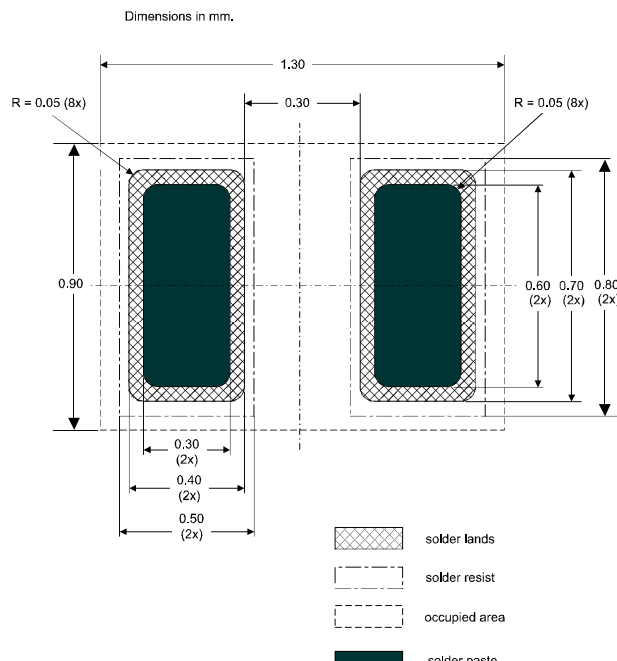
DFN1006-2			
Dim	Min	Max	Typ
A	0.95	1.075	1.00
B	0.55	0.675	0.60
C	0.45	0.55	0.50
D	0.20	0.30	0.25
G	0.47	0.53	0.50
H	0	0.05	0.03
N	—	—	0.40
R	0.05	0.15	0.10
All Dimensions in mm			

Marking, Polarity, Weight & Ordering Information

SBR02U100LP	Case Style (DFN1006-2)		Marking	Weight
	Top View	Back View	<div>• <u>2A</u></div> <div>• <u>2A</u></div>	0.001g (approx.)

Ordering Information	Date Code
SBR02U100LP-7 3000/Tape & Reel	<u>2A</u> , <u>2A</u> = Product Type Marking Code Dot Denotes Cathode Side

Suggested Pad Layout





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